

# Process steps for Field Emitter devices built on Silicon wafers And 3D Photovoltaics on Silicon wafers

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**Georgia Institute**  
**of Technology**

# Field Emitters



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**Doped Si**

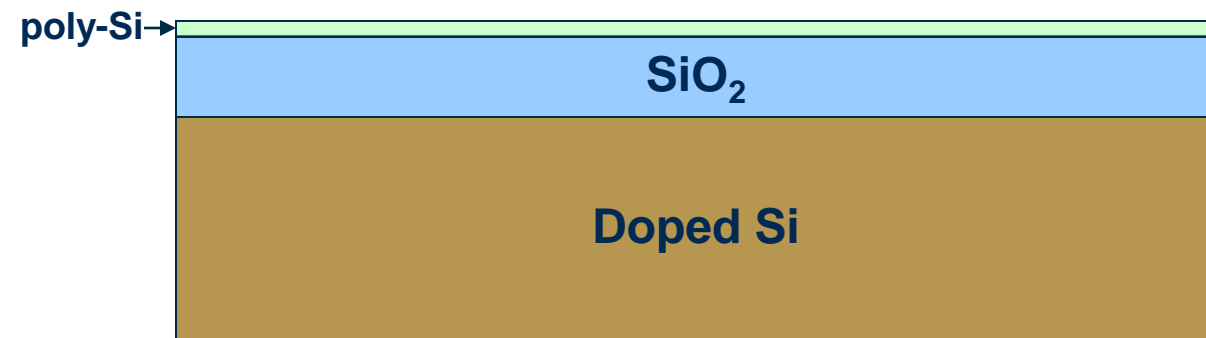


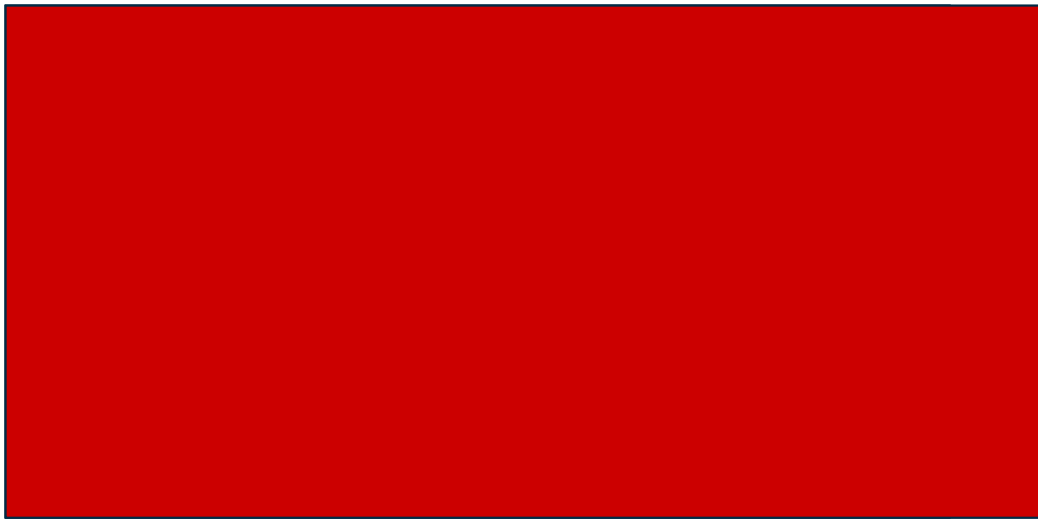


- Deposit SiO<sub>2</sub> (~10 μm)
- Variable for Height



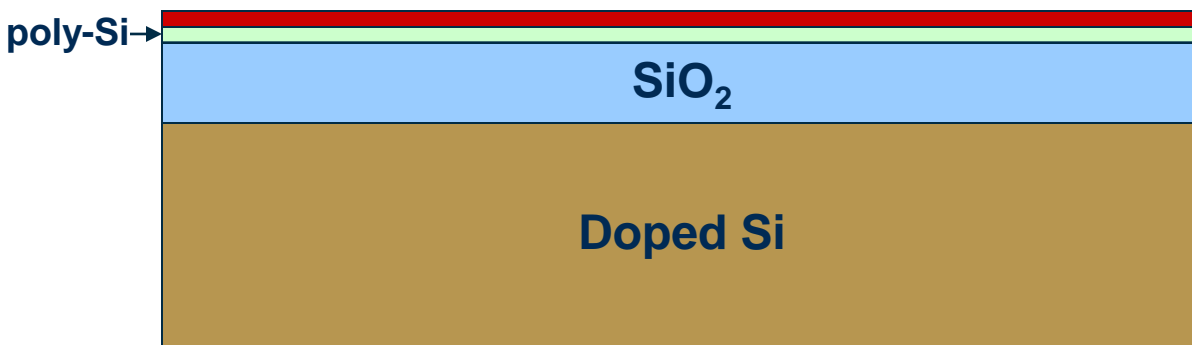
- Deposit gate
- (poly Si or Cr, ~200nm)





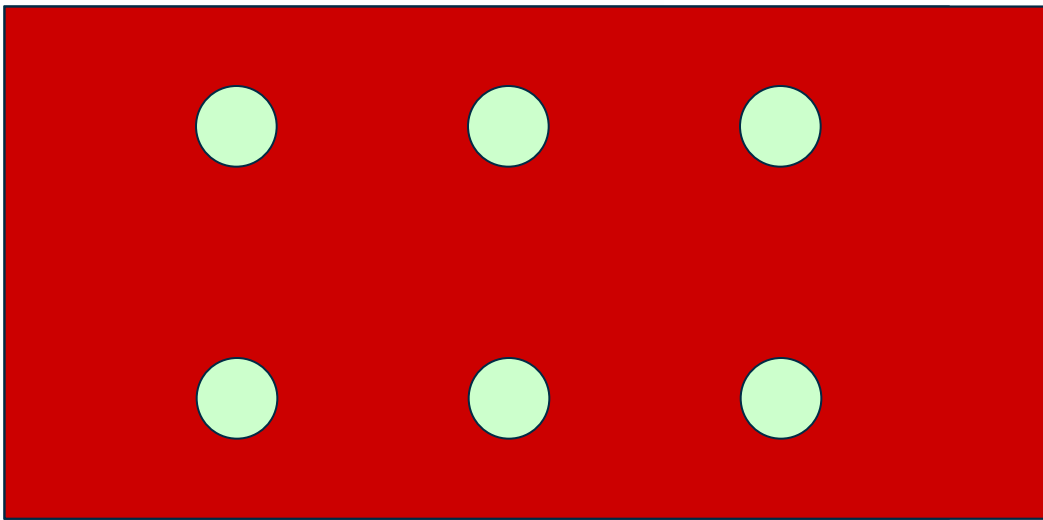
plan view

Spincoat Photoresist



elevation view





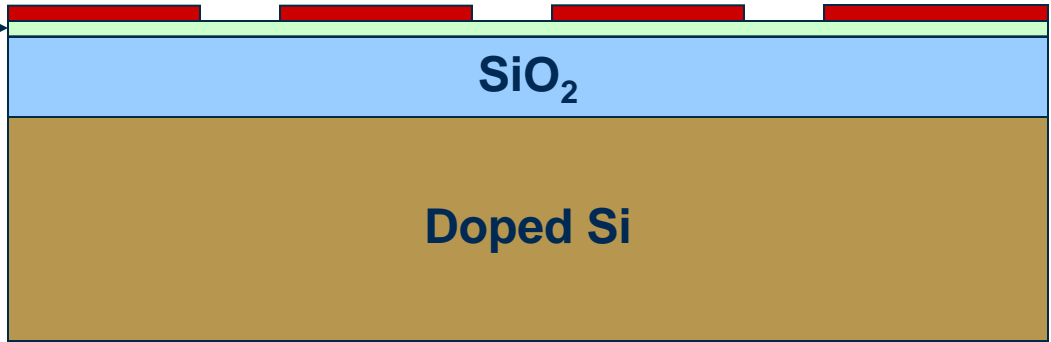
- Pattern
- Develop

plan view

Resist



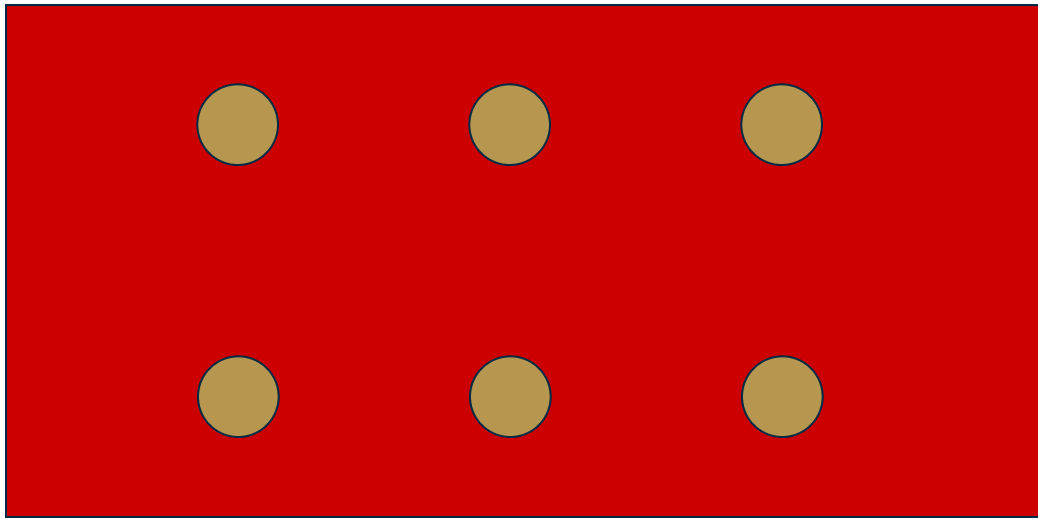
poly-Si



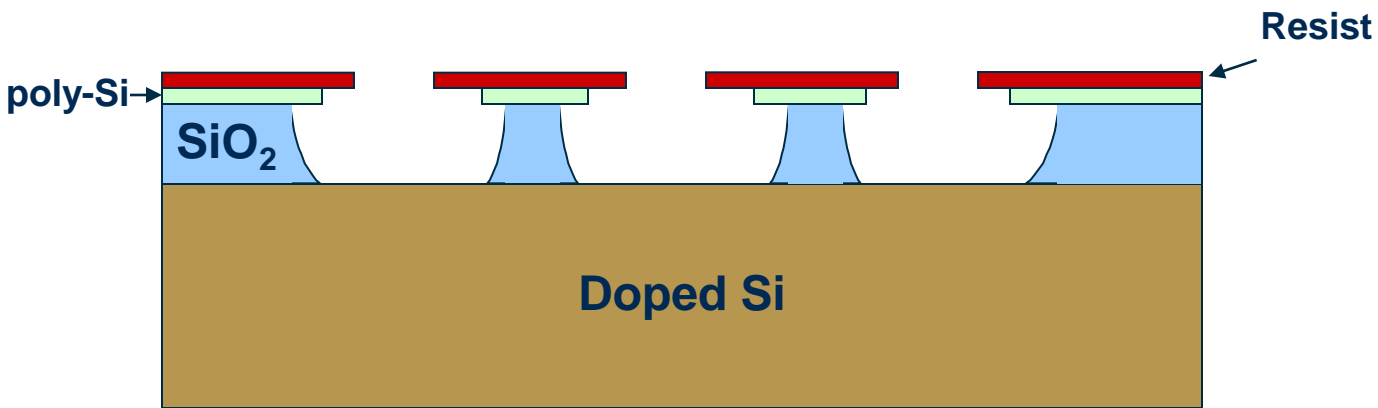
elevation view



•Etch gate and insulator isotropically



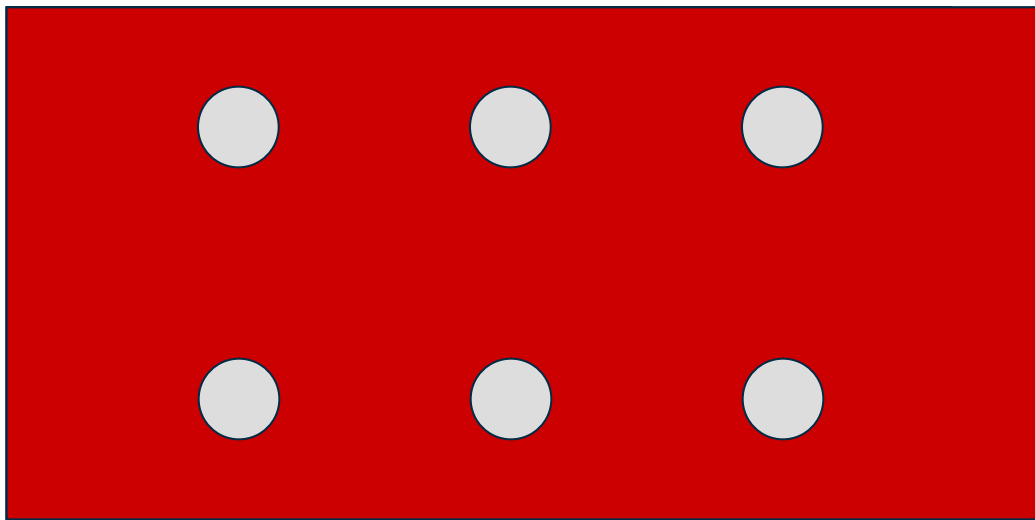
plan view



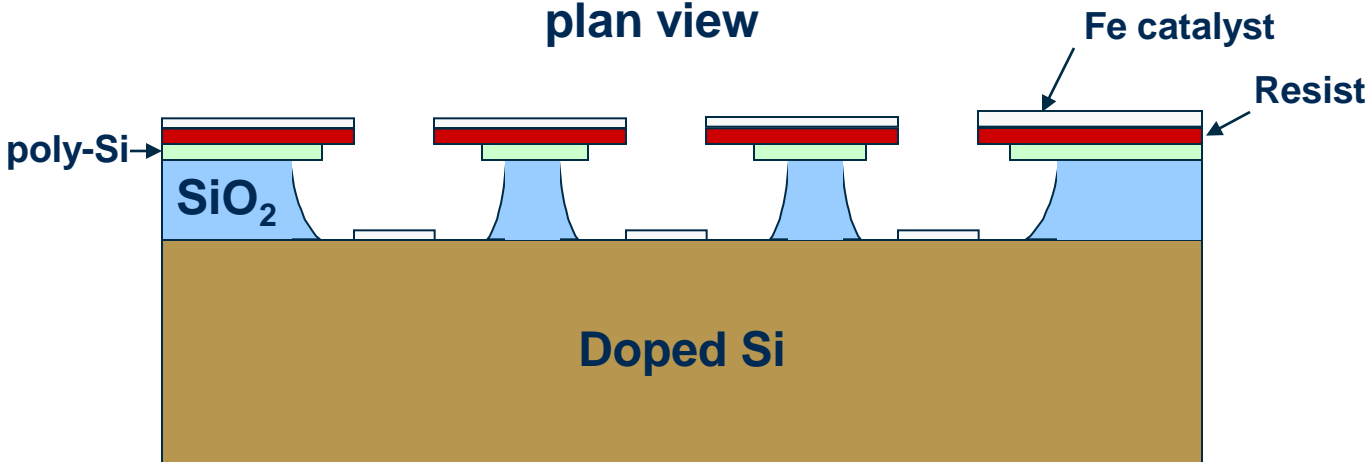
elevation view



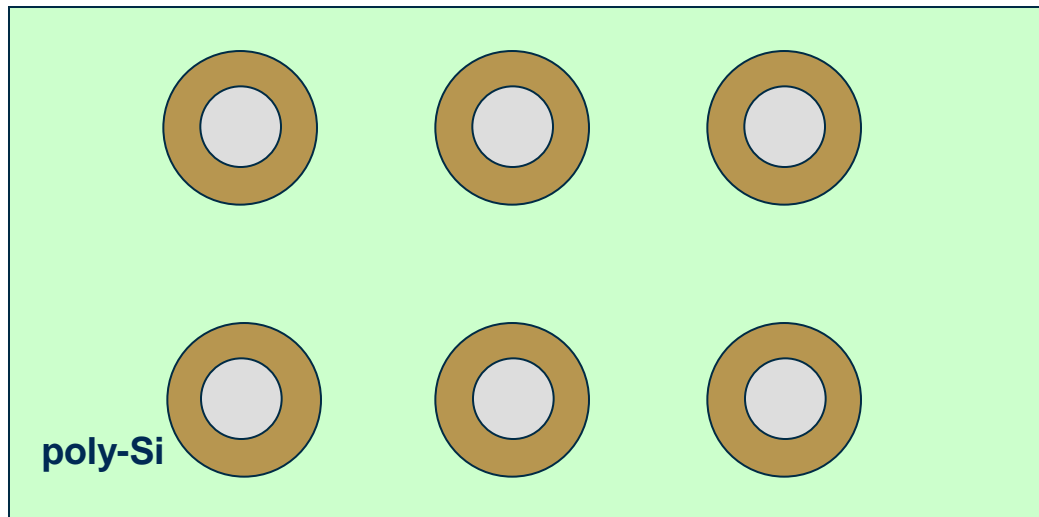
- Deposit catalyst metal
- Fe shown
- Ni possible with barrier layers



plan view

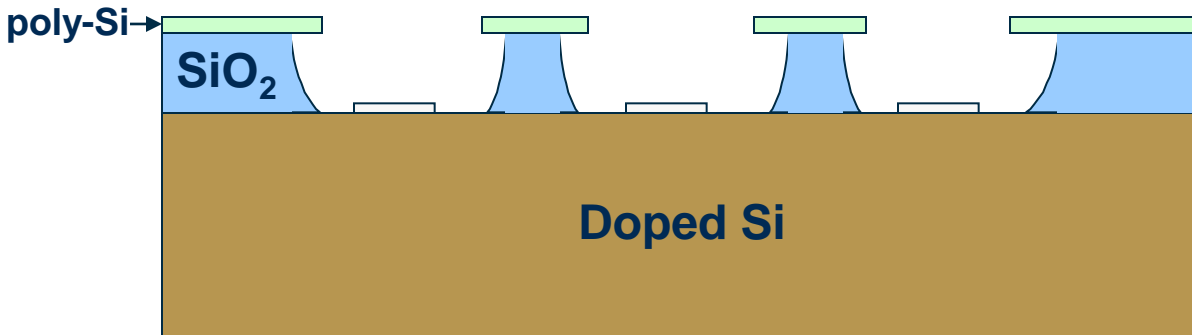


elevation view

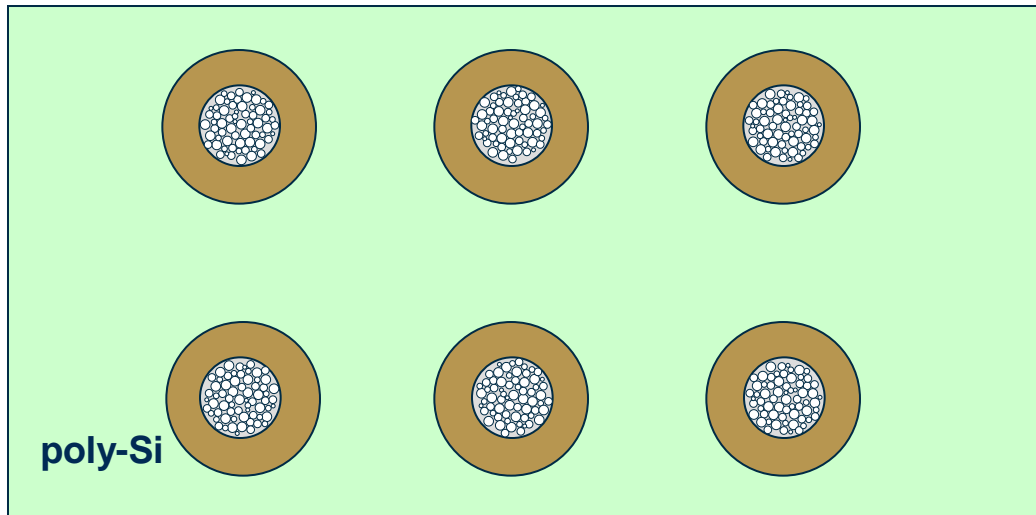


**Lift off & Dice**

**plan view**

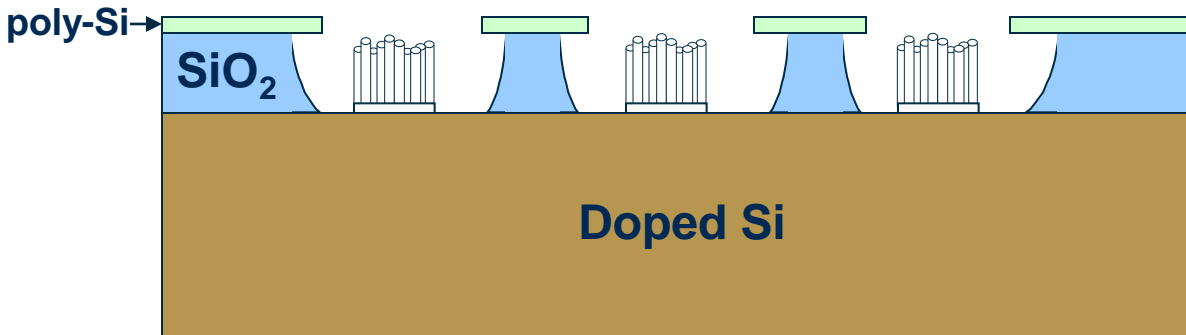


**elevation view**



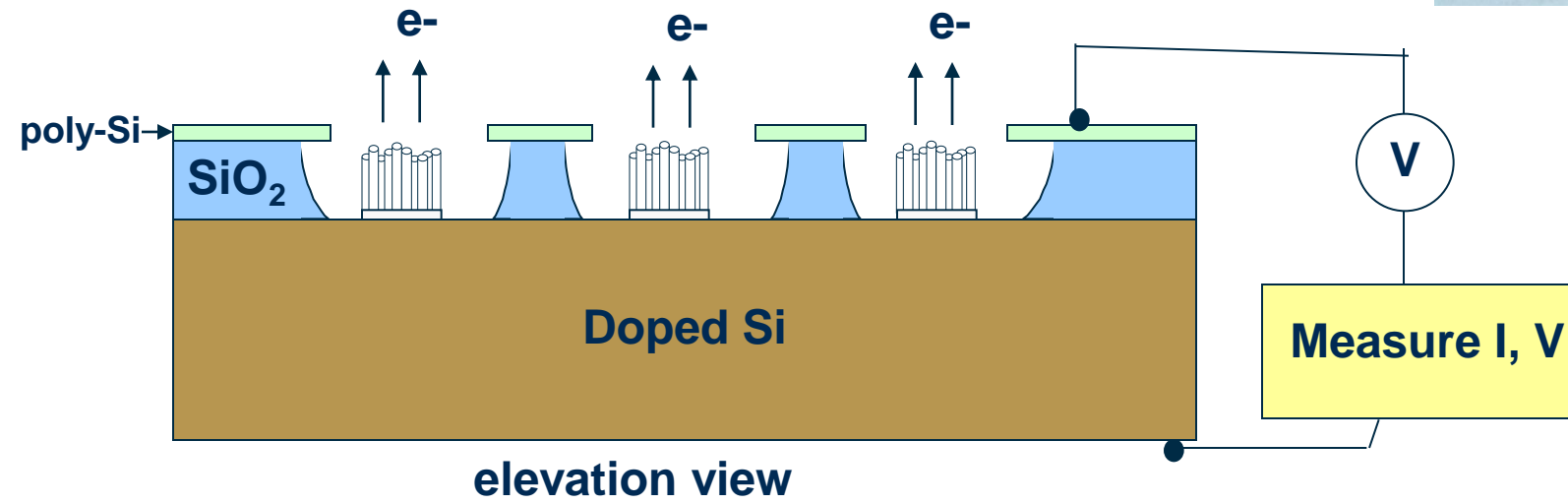
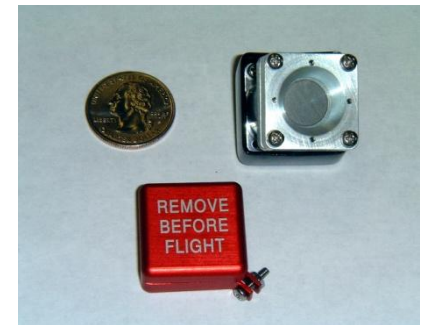
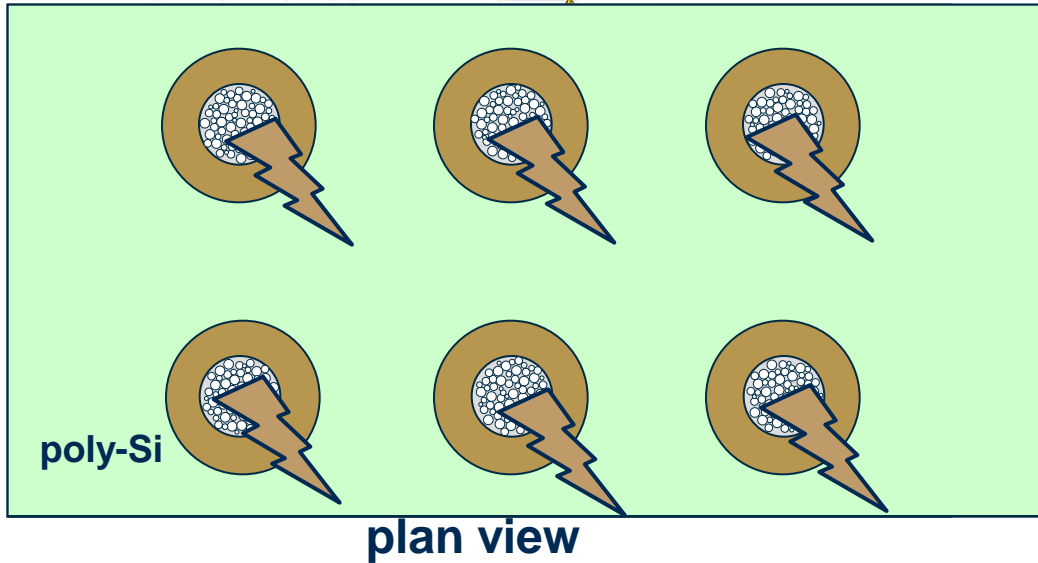
•Grow CNTs

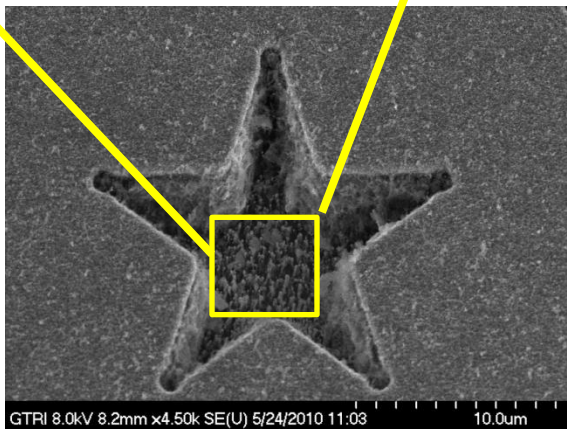
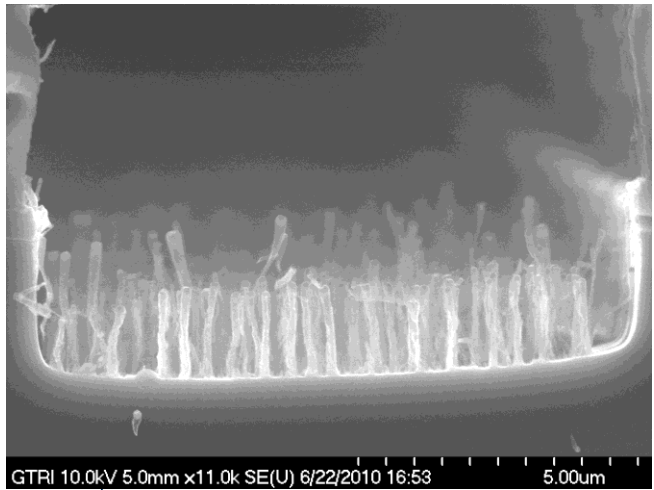
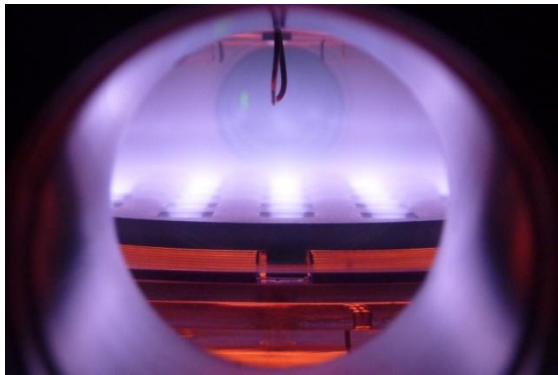
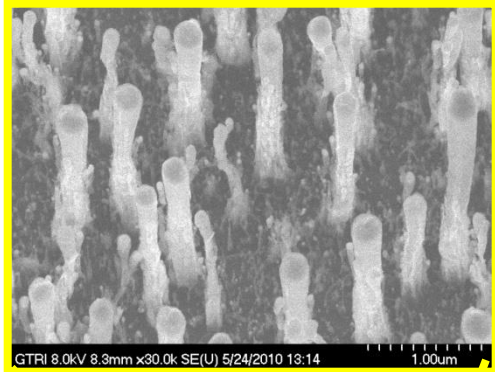
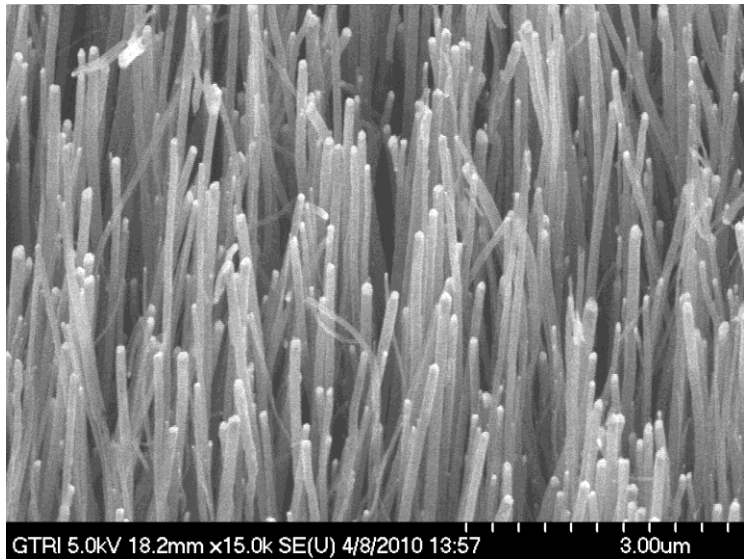
plan view



elevation view

- Connect and test @ HPEPL
- Langmuir Probe

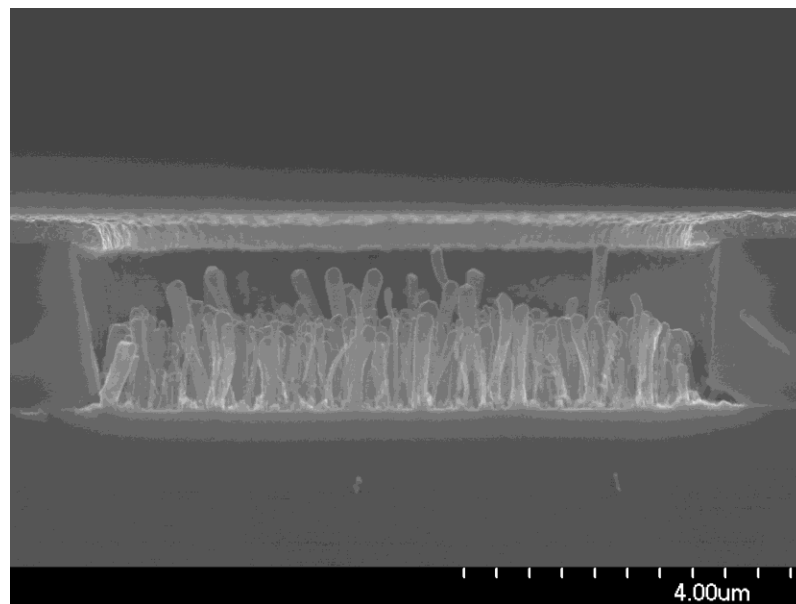
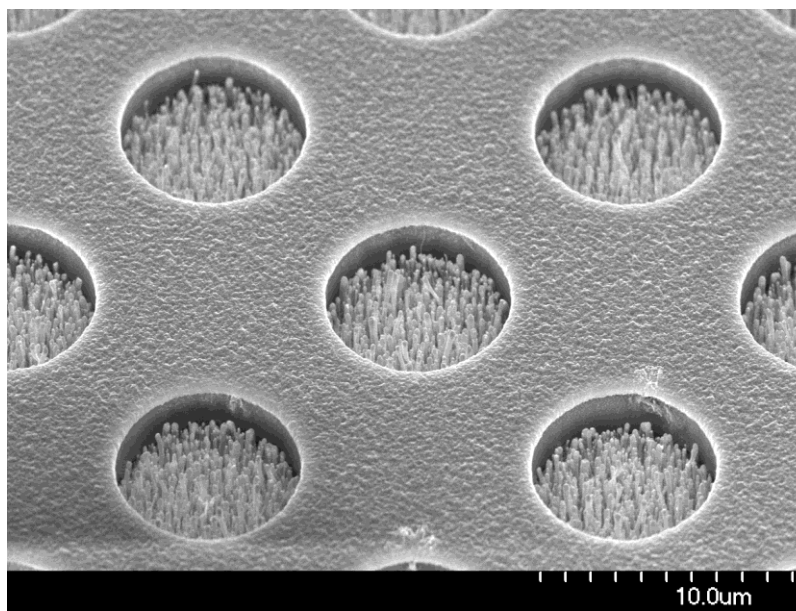




## CNT growth parameter for CNTs $\leq 2\mu\text{m}$

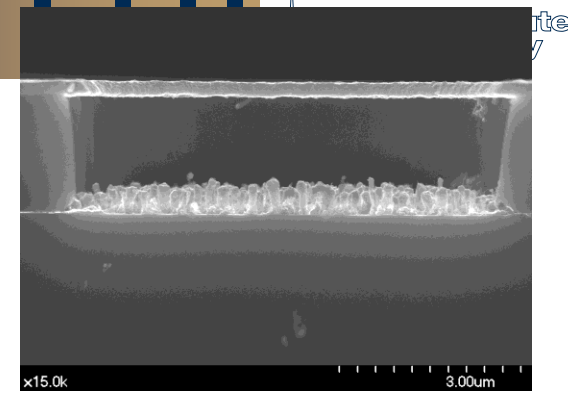
### CVD growth:

- $\text{N}_2$  and  $\text{NH}_3$  flowed at 100sccm and 160scmm
- Temperature ramp of  $300^\circ\text{C}/\text{min}$  until  $650^\circ\text{C}$  (top and bottom heat)
- Annealed at  $650^\circ\text{C}$  for 2min
- Plasma Ignited: 80W, 15kHz, 800V
- Pressure controller activated:  $P_{\text{chamber}} = 6\text{mbar}$
- Annealed under  $\text{NH}_3$  plasma for 3 min while T raised to  $750^\circ\text{C}$  at rate of  $200^\circ\text{C}/\text{min}$
- $\text{C}_2\text{H}_2$  (40sccm) introduced at end of plasma anneal
- Growth time = 6min
- Plasma extinguished, cooled under  $\text{N}_2$  flow until  $T < 400^\circ\text{C}$ . Opened to atmosphere

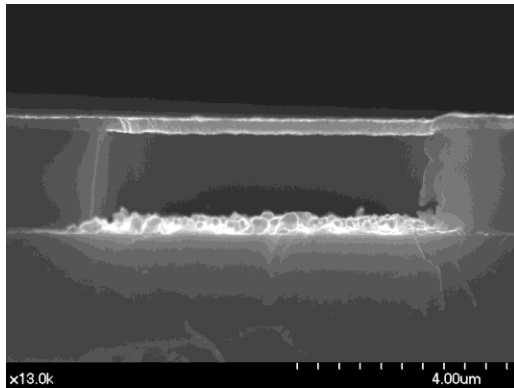


### Influence of Temperature on CNT growth

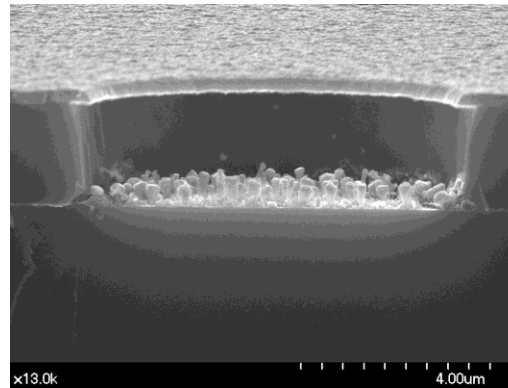
- Below **725 C** – Catalyst does not sufficiently create ‘synthesis islands’. Short, fat Carbon Fiber like ‘CNTs’ result
- Around **725 C** – islands initiate growth, but rate of growth is limited
- **750 C** - growth rate of  $\sim 0.3\mu\text{m}/\text{min}$
- **775 C** – some smaller islands, higher growth rate of smaller diameter CNTs
- **800 C** – increased Ni diffusion into Si, few catalyst island remain on surface, sparse CNT growth, much lower diameter. Rate is similar to 750-775 range with larger variance



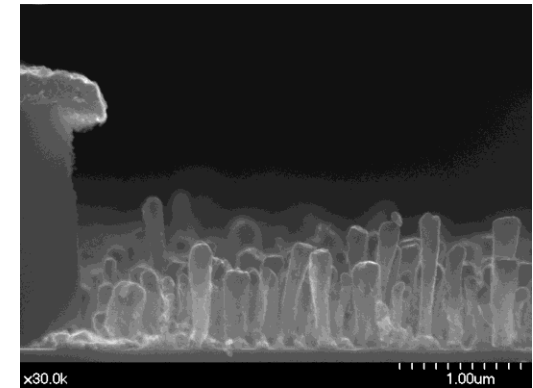
650 C



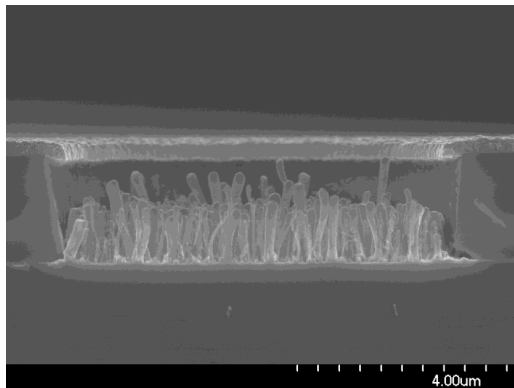
675 C



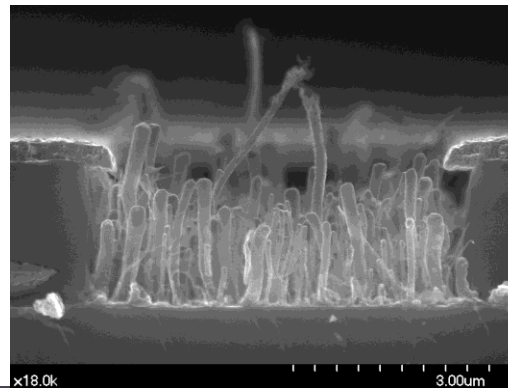
700 C



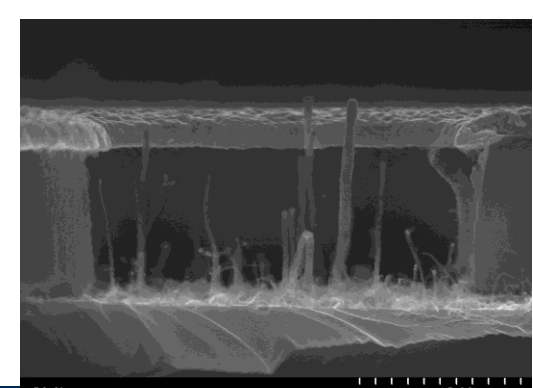
725 C



750 C

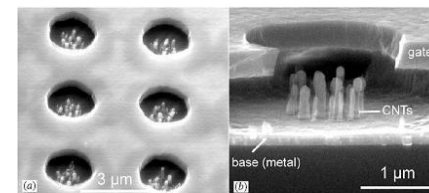
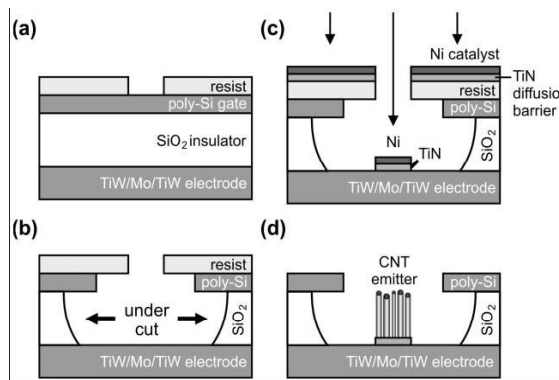
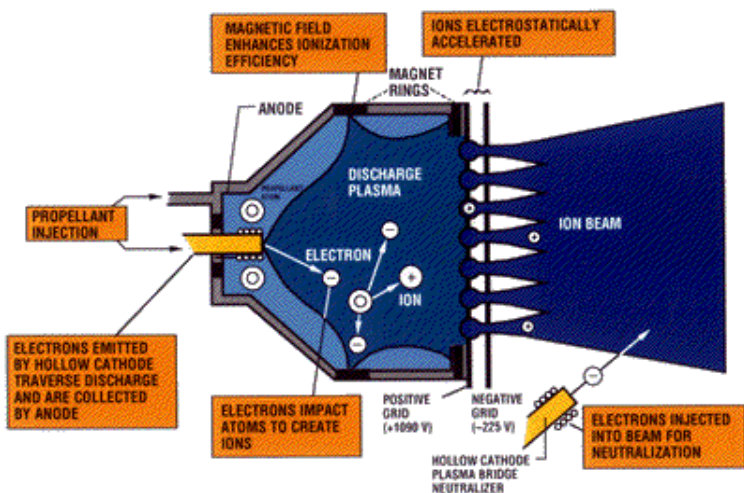


775 C



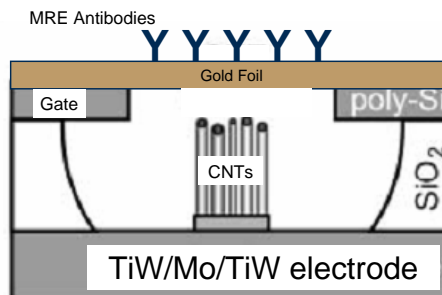
800 C

# Ion Electric Propulsion

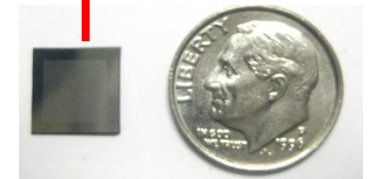
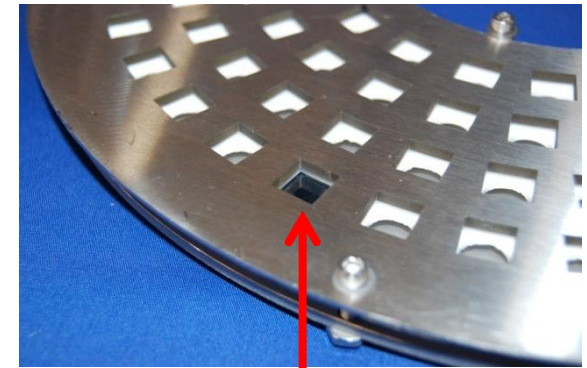
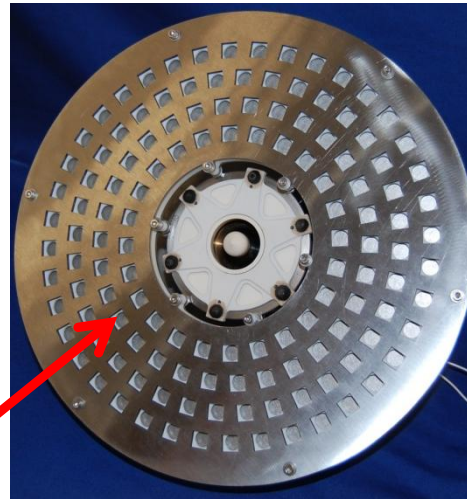
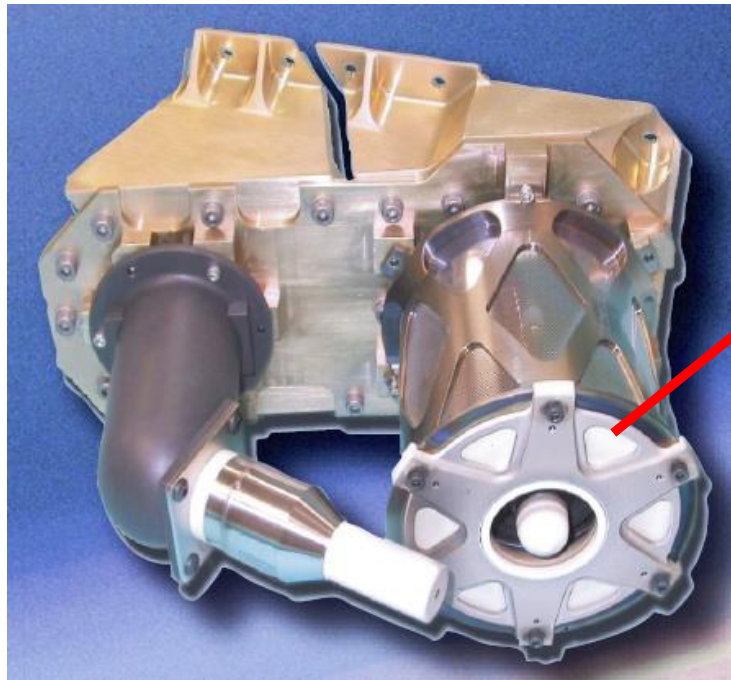


G. Piro, et al, *Nanotechnology*, vol. 13, pp. 1-4, 2002.

## Electron-induced Surface Plasmon Resonance (Chem-Bio Sensor)

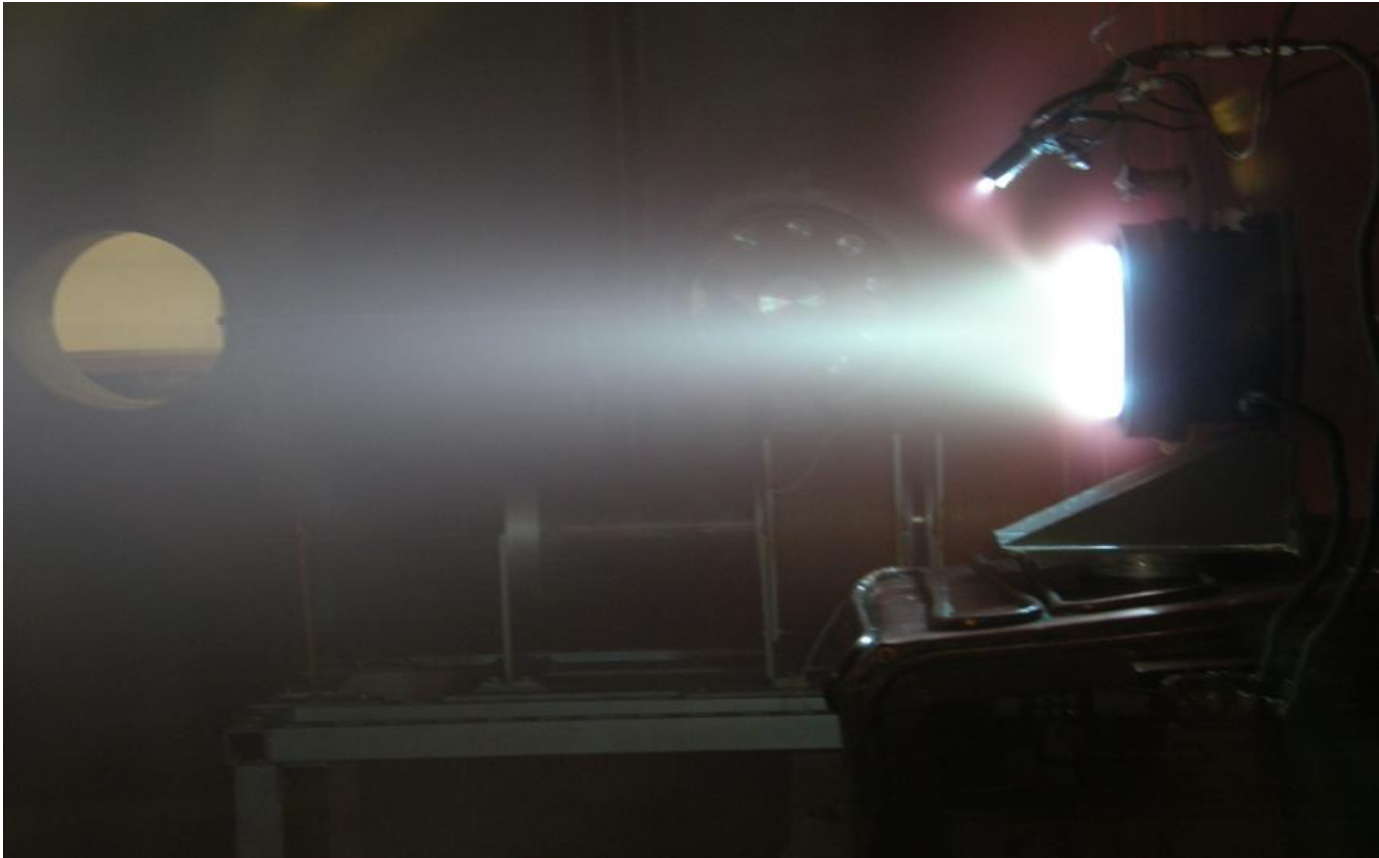






**84 Emitter Capacity**  
**2.1 A at 25 mA/cm<sup>2</sup>**

**Busek BHT-200 Modified  
for use with CNT Emitters**



**Thrust!**





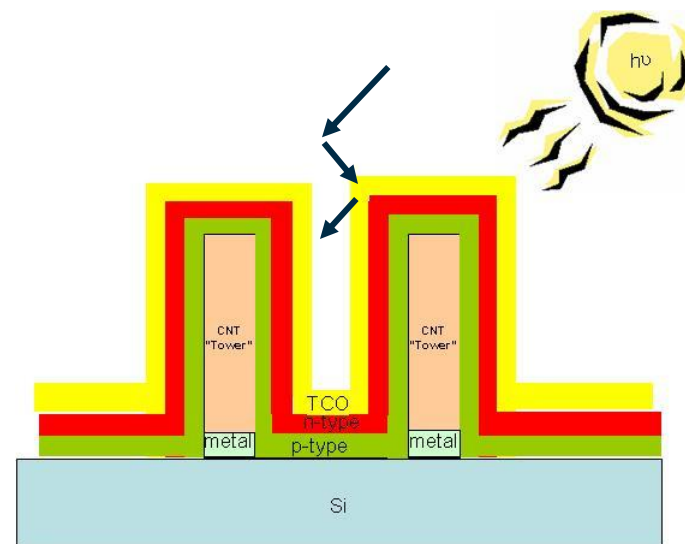
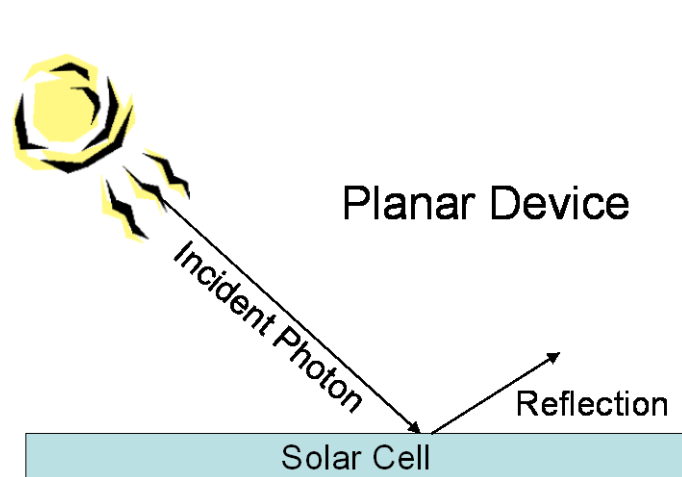
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# 3D Solar Cells

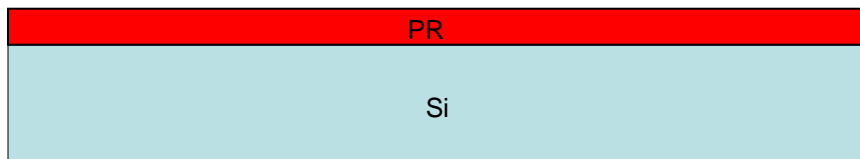
# Multiple bounce light trapping

- Light Trapping= more absorbance
- Thinner layers = less recombination
- “orthogonalize” absorption and carrier extraction
- Solves “thick-thin” conundrum

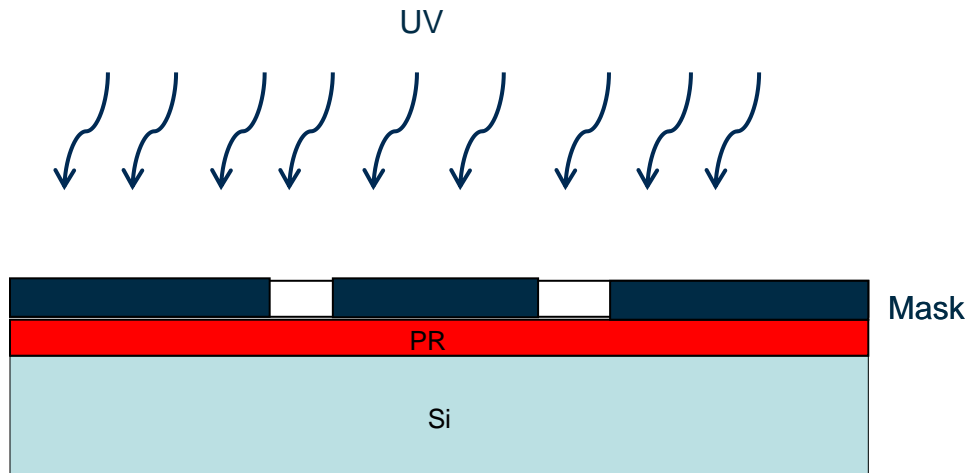


# CNT-Based Approach

- PR spun on



# CNT-Based Approach



- PR spun on
- Mask and expose to UV

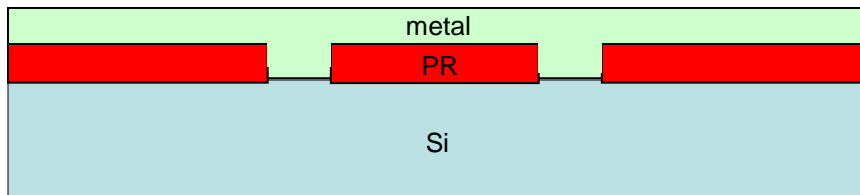
# CNT-Based Approach

- PR spun on
- Mask and expose to UV
- Develop PR



# CNT-Based Approach

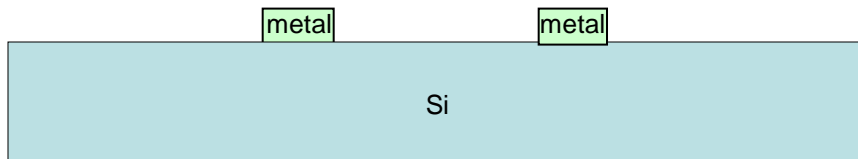
- PR spun on
- Mask and expose to UV
- Develop PR
- Fe deposited





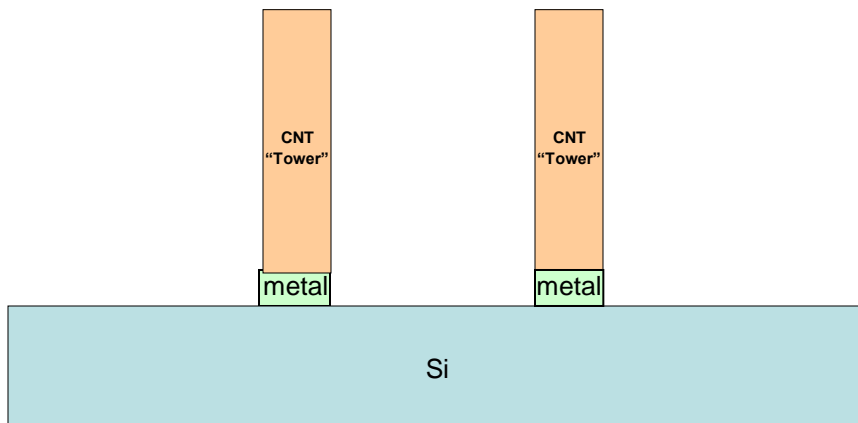
# CNT-Based Approach

- Pattern generated on Si substrate via photolithography
- Metal catalyst (Fe) applied
- Lift-off photoresist to leave only patterned catalyst



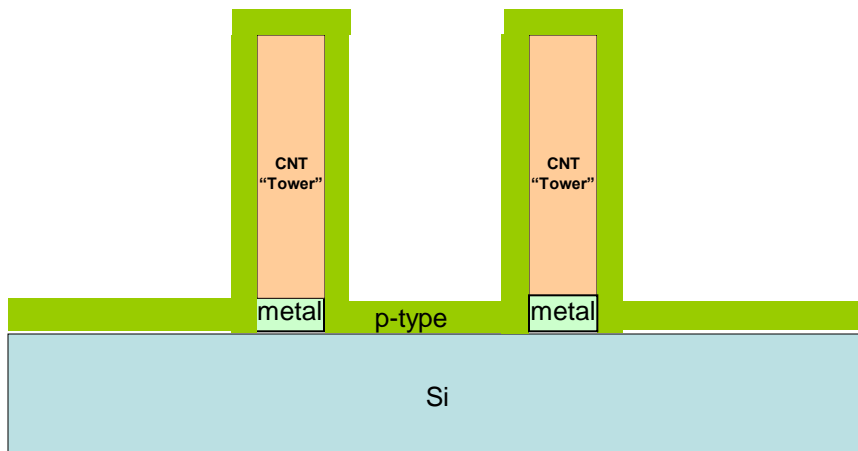
# CNT-Based Approach

- Pattern generated on Si substrate via photolithography
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- CNT towers are formed in Chemical Vapor Deposition (CVD) furnace (~720°C; 20 min.)

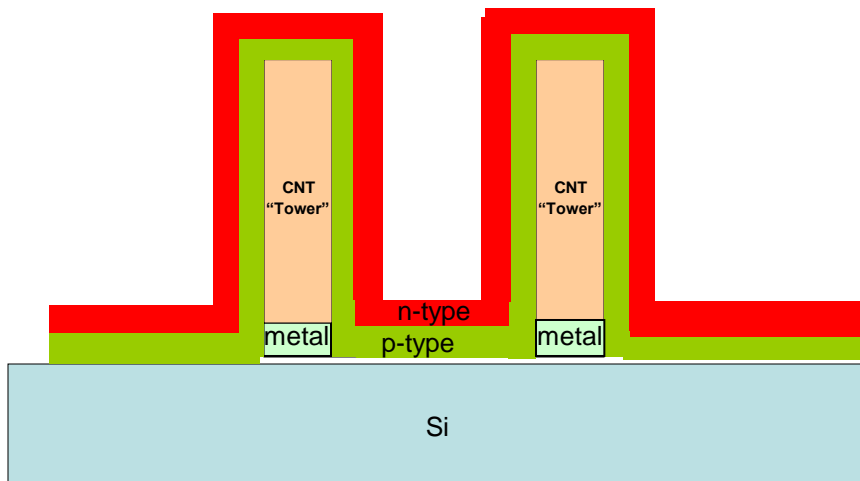


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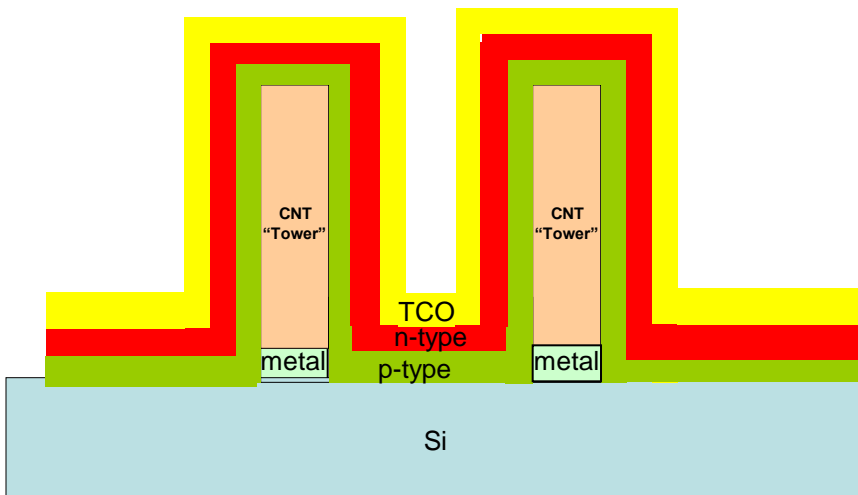


# CNT-Based Approach



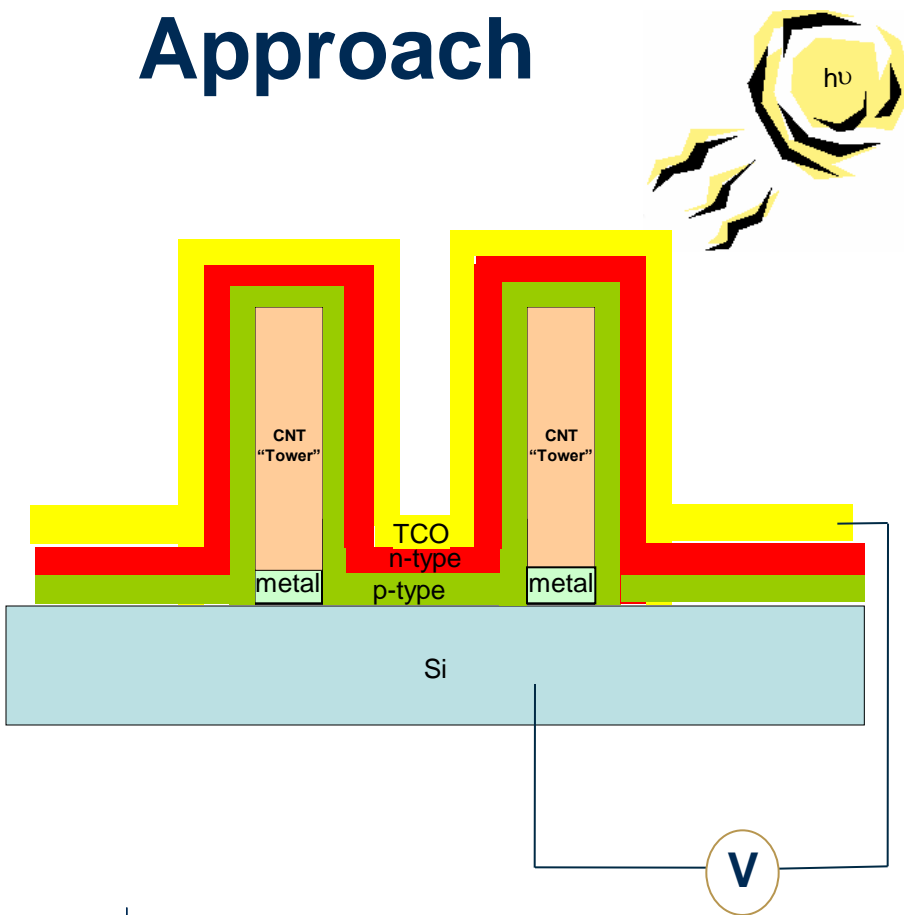
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- n-type material (CdS) applied via MBE or CBD

# CNT-Based Approach



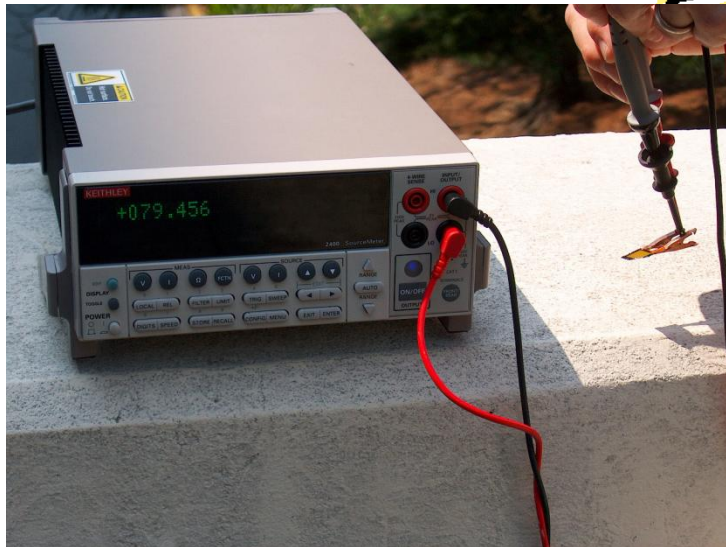
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# CNT-Based Approach



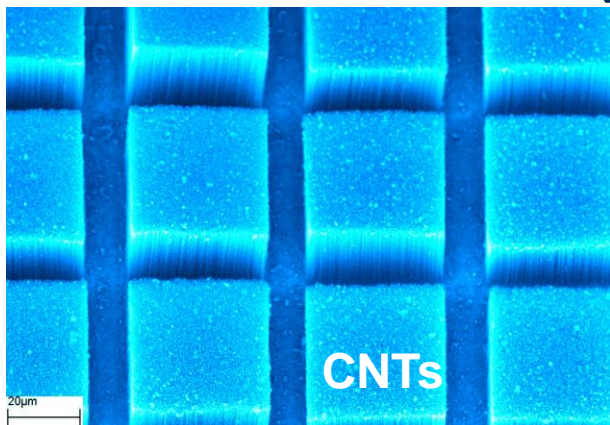
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# CNT-Based Approach

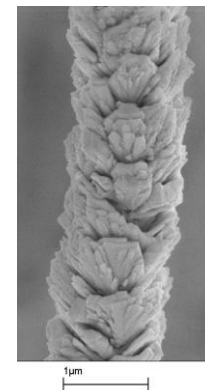
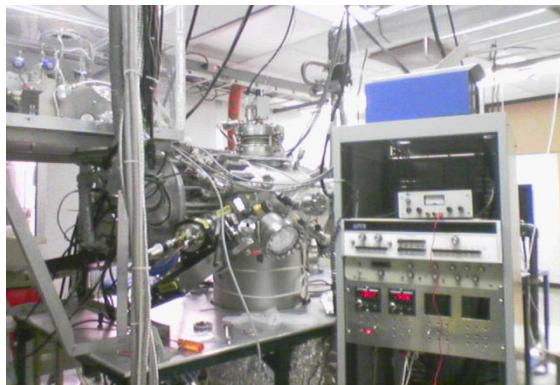
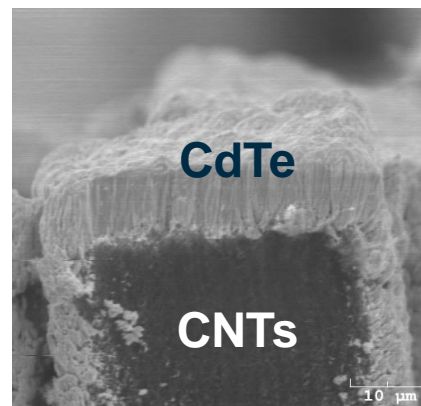


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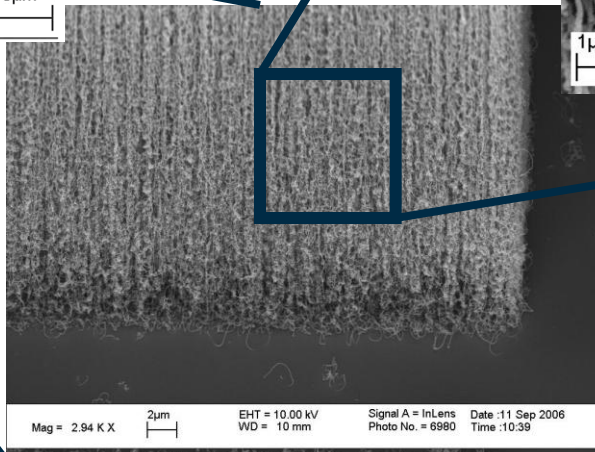
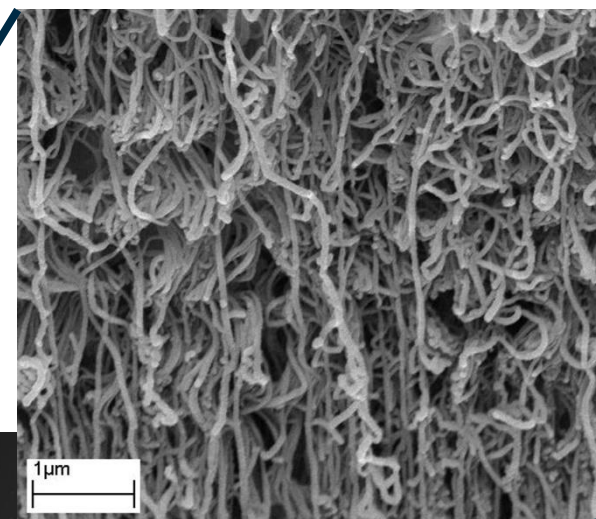
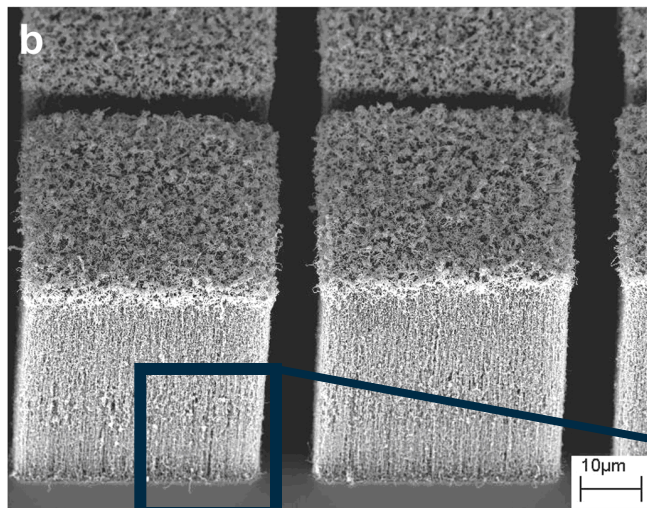
# Molecular Beam Epitaxy for CdTe and CdS deposition (p/n junction)

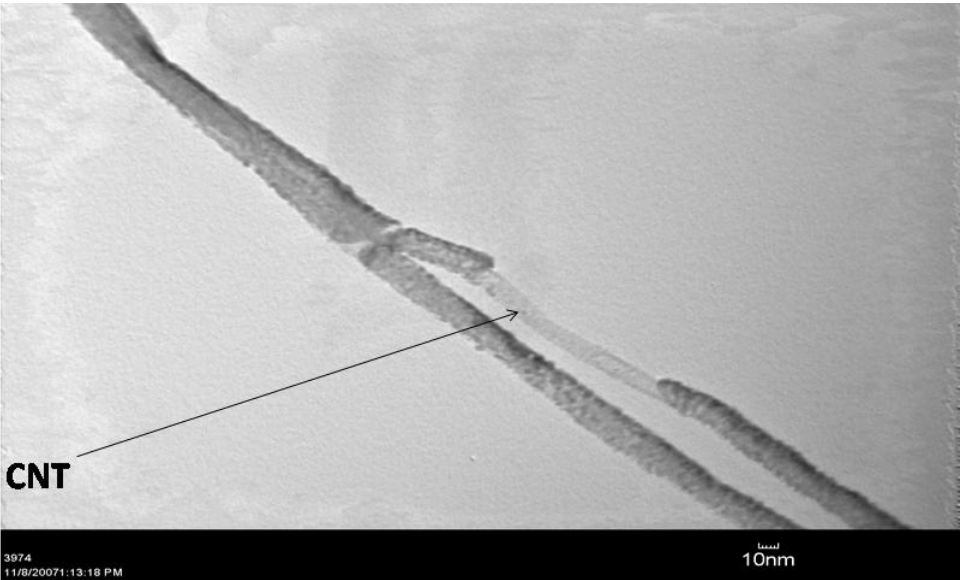
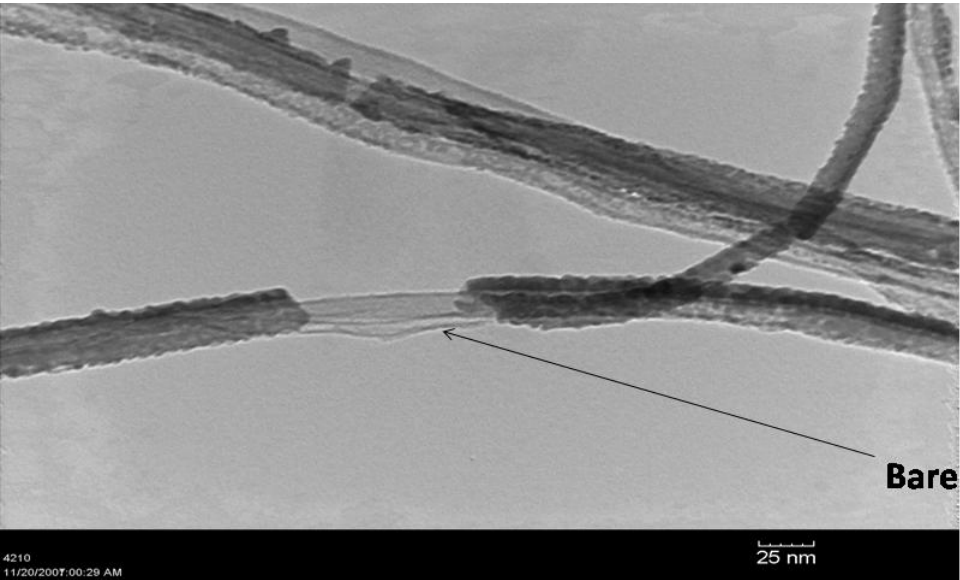


Si substrate



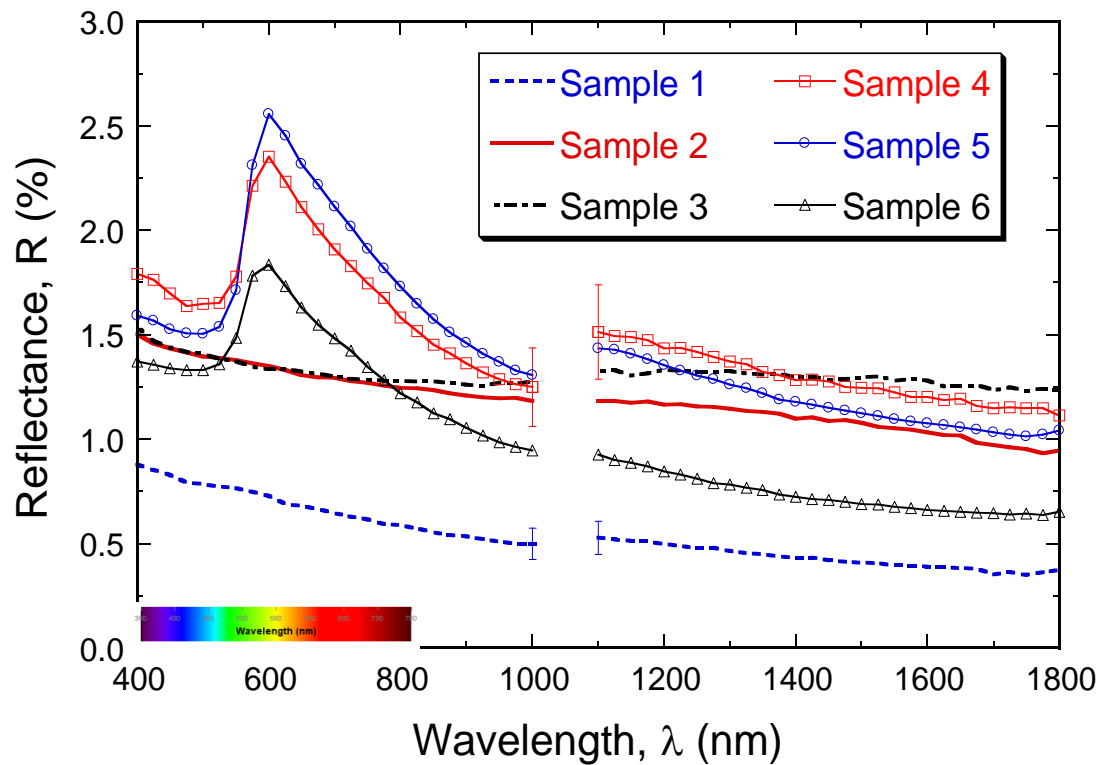
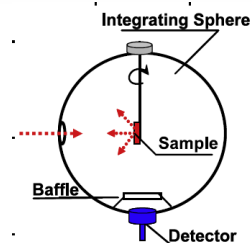






**Bare CNT**

# Light Reflection



EOP/Plasmonics  
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doi:10.1016/j.nanot.2009.03.001

## Visible and near-infrared radiative properties of vertically aligned multi-walled carbon nanotubes

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### Abstract

This work investigates the reflection and scattering from vertically aligned carbon nanotubes, fabricated on silicon substrate using thermally enhanced chemical vapor deposition with both tip-growth and base-growth mechanisms. The directional-hemispherical reflectance in the visible and near-infrared wavelengths was measured with an integrating sphere. The polarization-dependent bidirectional reflectance distribution function was characterized with a laser scatterometer at the wavelength of 635 nm. The effective medium theory was used to elucidate the mechanism of high absorbance (greater than 0.97 in the spectral region from 400 to 1500 nm) of the multi-walled carbon nanotube samples. It is observed that scattering by impurities on the top of the nanotubes, by the nanotube tips, and by defects and misalignment can significantly increase the reflectance and introduce retroreflection. This study may facilitate application of carbon nanotubes in pyroelectric detectors as well as thermophotovoltaic emitters and absorbers.

(Some figures in this article are in colour only in the electronic version)

### Nomenclature

Nomenclature	Greek symbols	absorbance
$a$	$\alpha$	complex dielectric function
$C$	$\beta$	polar angle of incidence or observation, deg
$d$	$\theta_{w,0}$	extinction coefficient
$f$	$\lambda$	wavelength, nm
$f_r$	$\rho_s$	reflectivity at the interface
$n$	$\theta_{det}$	solid angle of the detector, sr
$H$		
$R$		
$R_{dir}$		
$S_{A,B}$		
$T$		
$x$		

### 1. Introduction

The growing research activities on carbon nanotubes (CNTs) have recently led to broad applications for pyroelectric detectors, solar cells, bolometers, and other photonic devices [1–8]. The extensive applications of CNTs are a consequence of the unique properties that result from their

<sup>5</sup> Author to whom any correspondence should be addressed.

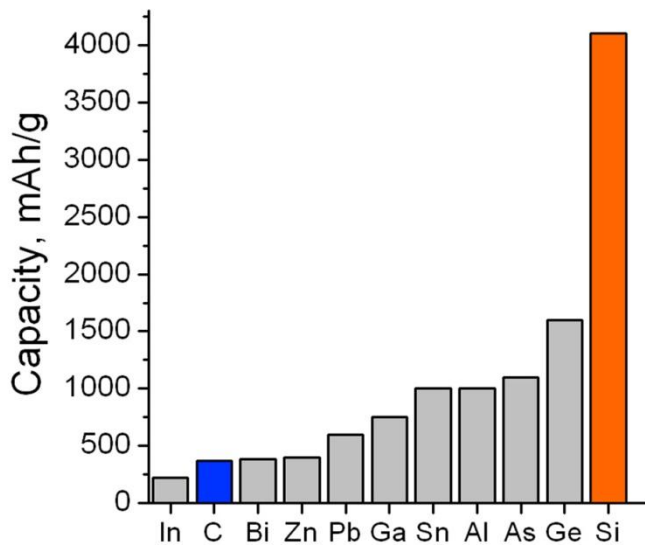


# Extra Slides on CNT Batteries



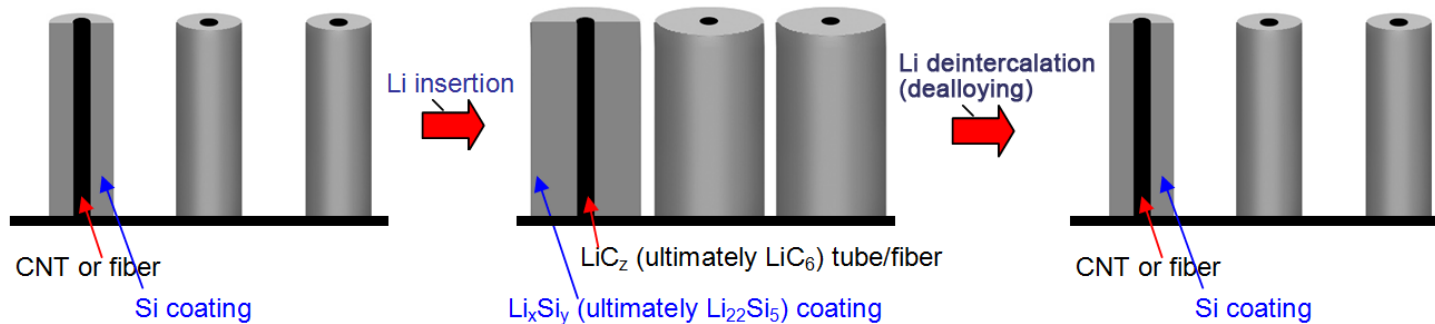
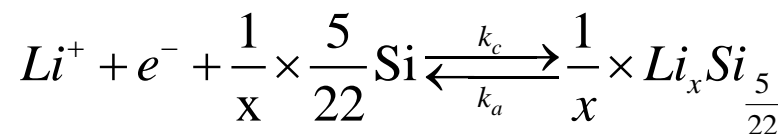
# Si-coated Carbon Nanotubes for Li-ion battery anodes

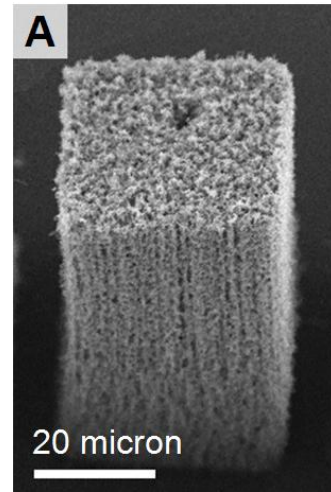
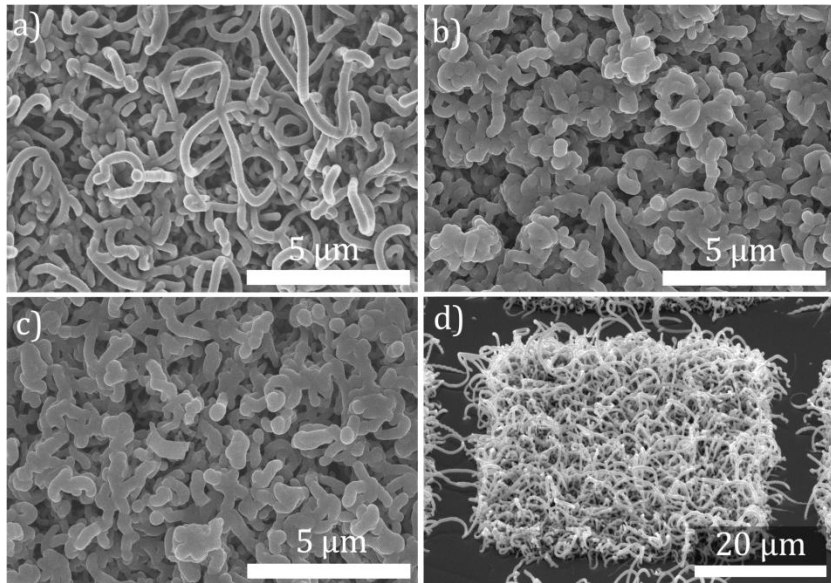
(with Yushin in MSE)



Vertically aligned carbon nanotubes or fibers coated with Si

- Silicon has an order of magnitude greater capacity compared to graphite anodes
- But Silicon has very poor cyclability (pulverizes with Lithium insertion)
- Solution = Reinforce Silicon (with Carbon Nanotubes)

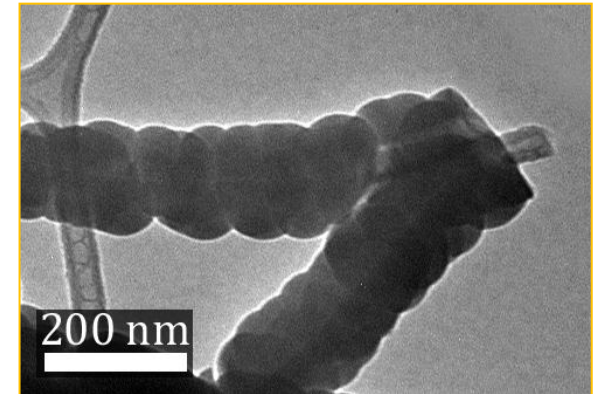
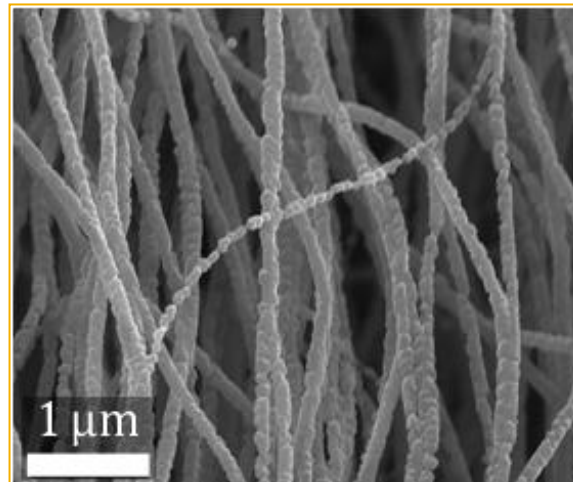




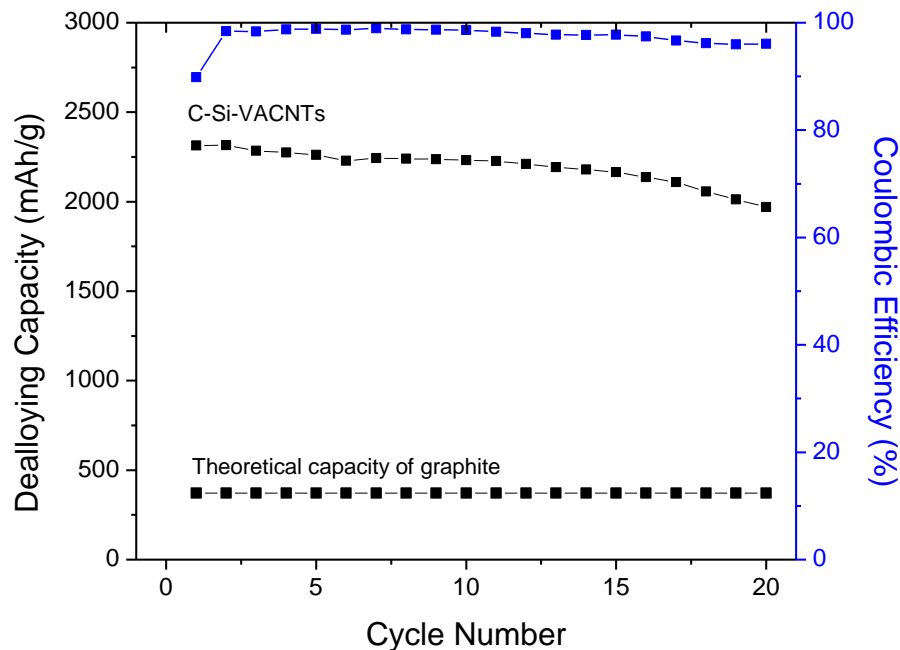
**Vertically aligned carbon nanotubes**

**Act as “rebar” to strengthen internal structure of Si-battery**

**Pictures of Si-coated Carbon Nanotubes Demonstrates conformal coatings are possible**



# Charge/Discharge Results



- Stable performance and reversible dealloying capacity in excess of 2000 mAh/g (over 5x more than graphite) has been demonstrated.
- VACNTs provide structural support for Si as well as dramatically improved electrical conductivity therefore higher power Si-containing electrodes are possible.

# Patterned & Aligned CNTs

- Sensors
- Cultures
- Scaffolds
- Heat Sink
- Batteries
- Fuel Cells
- Logic circuits
- Hydrogen storage
- Waveguide/Filter
- Many, MANY more . . .

